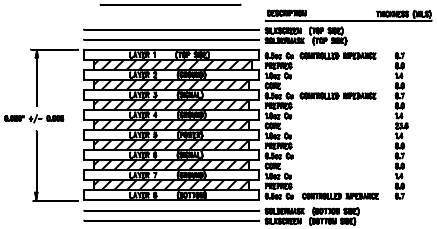
REVISIONS				
REV	ECN	DESCRIPTION	DATE	INCORP

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994
   ALL DIMENSIONS IN INCHES.
2. FABRICATE IN ACCORDANCE WITH IPC-6011 & IPC-6012.
3. MATERIAL: FR-4, GREEN COPPER CLAD GLASS EPOXY OR EQUIV.
   COPPER WEIGHT TO BE: 0.5 OZ. ON EXTERNAL LAYERS.
   0.5 OZ. ON INTERNAL SIGNAL LAYERS.
   1 OZ. ON PLANE LAYERS.
   LAMINATE USING PRE-PREG MATERIAL PER IPC-4101.
4. MIN TRACE AND SPACING THICKNESS: TRACE 0.009, SPACE 0.009
5. ALL PLATED THROUGH HOLES TO HAVE A MIN OF .001 COPPER.
   ALL DIMENSIONS APPLY AFTER PLATING.
6. ALL HOLES LOCATED WITHIN .005 OF TRUE POSITION. LAYER TO LAYER REGISTRATION SHALL BE WITHIN .003.
7. MAXIMUM WARP AND TWIST IS .010 IN/IN.
8. REMOVE ALL BURRS AND SHARP EDGES.
9. SOLDERMASK WITH LPI, COLOR: GREEN, OVER BARE COPPER PER IPC-SM-840.
   VIAS MAY BE FILLED. MAX REGISTRATION IS WITHIN .005. SOLDERMASK GERBER DATA IS 1:1. WITH ACTUAL PADS SIZE. PAD OVERSIZE NOT TO EXCEED .003.
10. SILKSCREEN TO BE NON-CONDUCTIVE INK, COLOR: WHITE.
11. SOLDER COATING (HOT AIR SOLDER LEVELING):
    HOLES AND PADS SHALL BE SOLDER COATED USING HOT AIR LEVELING METHOD AFTER APPLICATION OF SOLDER MASK. THE TIN-LEAD ALLOY RATIO SHALL BE 60/40%. THE SOLDER COATING THICKNESS SHALL BE A MINIMUM OF .00010. AND EVEN IN APPEARANCE. DE-WETTING AND NON-WETTING ARE NOT ACCEPTABLE AND SHALL BE CAUSE FOR REJECTION PER IPC-A-600.
12. MANUFACTURER'S UL AND DATE CODE TO BE PLACED ON BOTTOM SIDE OF BOARD.
13. THIS IS A CONTROLLED IMPEDANCE PCB, TARGETED TRACE IMPEDANCES ARE 90 OHMS AND 100 OHMS. REFER TO CONTROLLED IMPEDANCE TABLE FOR MORE DETAILED INFORMATION. IT IS FABRICATOR'S RESPONSIBILITY TO INSURE IMPEDANCE COMPLIANCY TO WITHIN 10% OF TARGETED IMPEDANCE. TRACE WIDTHS AND DIELECTRIC THICKNESSES CAN BE MODIFIED TO ACHIEVE COMPLIANCY. SEE LAYER STACK DETAIL.

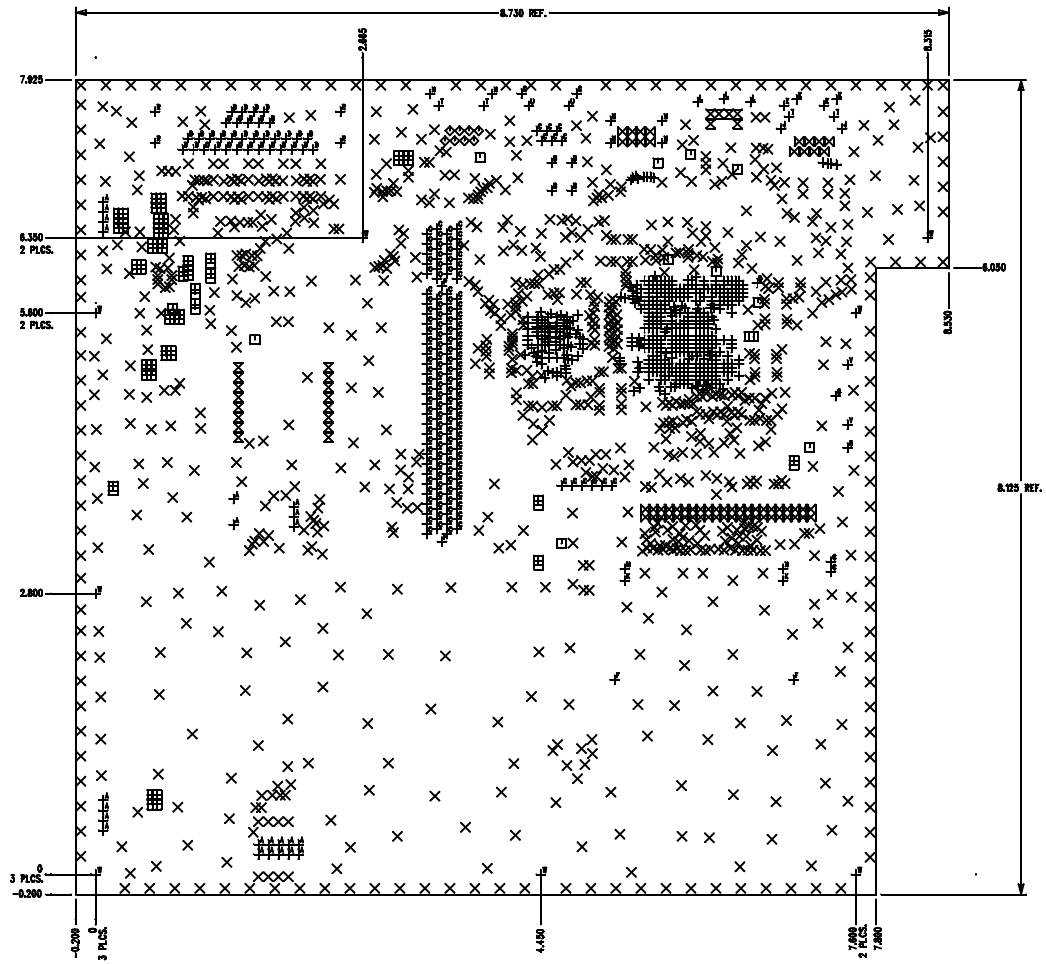
LAYER STACK DETAIL



13. CONTROLLED IMPEDANCE TABLE

(ONLY VALUES SPECIFIED ARE APPLICABLE)

TRACE / SPACING	TARGET Z OHMS +/- 10%	SUPPLIED CAD DATA TRACE WIDTH, MILS		
		MICROSTRIP	STRIPLINE	LAYER(S)
DIFFERENTIAL PAIR	90	10.1 / 8.0	NA	1, 8
DIFFERENTIAL PAIR	90	NA	7.3 / 8.0	3
DIFFERENTIAL PAIR	100	9.0 / 8.0	NA	1, 8



SIZE	QTY	SYM	PLATED	TOL
0.01	521	+	YES	+/-0.003
0.012	1084	X	YES	+/-0.003
0.018	99	□	YES	+/-0.003
0.032	8	◇	YES	+/-0.003
0.035	22	⊠	YES	+/-0.003
0.036	60	⋈	YES	+/-0.003
0.037	23	⊣	YES	+/-0.003
0.038	4	⊣	YES	+/-0.003
0.04	134	⊣	YES	+/-0.003
0.043	35	⊣	YES	+/-0.003
0.047	4	⊣	YES	+/-0.003
0.053	2	⊣	NO	+/-0.003
0.056	4	⊣	YES	+/-0.003
0.059	2	⊣	YES	+/-0.003
0.062	2	⊣	YES	+/-0.003
0.069	2	⊣	NO	+/-0.003
0.09	3	⊣	YES	+/-0.003
0.091	4	⊣	YES	+/-0.003
0.092	2	⊣	YES	+/-0.003
0.098	2	⊣	NO	+/-0.003
0.121	4	⊣	YES	+/-0.003
0.125	4	⊣	NO	+/-0.003
0.128	2	⊣	NO	+/-0.003
0.136	2	⊣	NO	+/-0.003
0.172	8	⊣	YES	+/-0.003

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Engineer: Hamilton Ward
PCB Design Centers
www.esdserv.com
Date: 8-14-15

ESD Services
12841 Jamieson Road
Prosp, CA 92064
1-800-745-3282

Project: MONEY ORDER II SINGLE BOARD COMPUTER

FABRICATION DRAWING — Rev: D

CAD FILE: 359-000370-1_Fabdrwgdm — SCALE: 1/1

PCB NO: 000370 — PCB: 359-000370-1pcb — 1 OF 1